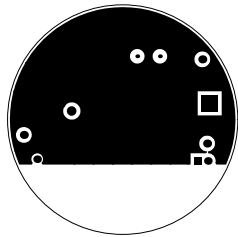
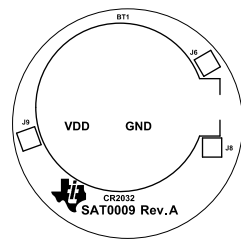


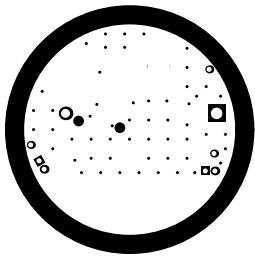
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidBaged20outline			
PLOT NAME = MidLayer2	GENERATED : 7/19/2013 2:30:22 PM	TEXAS INSTRUMENTS	



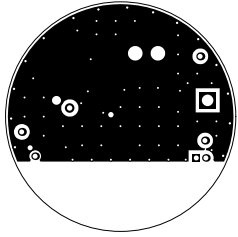
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidBaged10Outline			
PLOT NAME = MidLayer1	GENERATED : 7/19/2013 2:30:23 PM	TEXAS INSTRUMENTS	



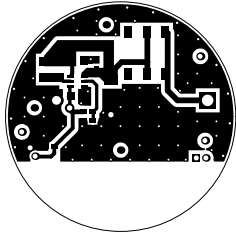
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/19/2013 2:30:24 PM	TEXAS INSTRUMENTS	



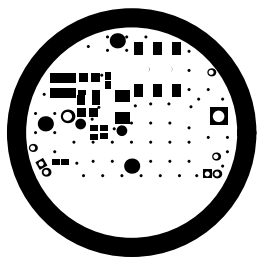
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/19/2013 2:30:24 PM	TEXAS INSTRUMENTS	



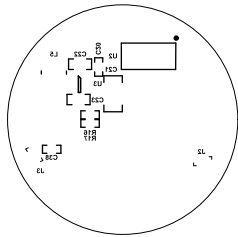
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 7/19/2013 2:30:25 PM	TEXAS INSTRUMENTS	



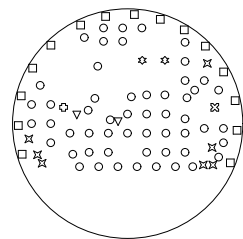
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/19/2013 2:30:26 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/19/2013 2:30:26 PM	TEXAS INSTRUMENTS	



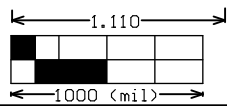
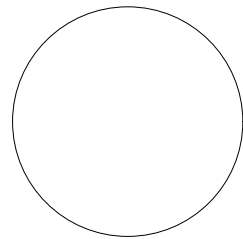
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 7/19/2013 2:30:27 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	54	10mil (0.254mm)	PTH	Round
□	15	12mil (0.305mm)	PTH	Round
⊗	7	26mil (0.66mm)	PTH	Round
▽	2	28mil (0.711mm)	PTH	Round
☆	2	35.433mil (0.9mm)	NPTH	Round
⊙	1	46.5mil (1.181mm)	PTH	Round
⊗	1	60mil (1.524mm)	PTH	Round
	82 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/19/2013 2:30:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0009	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 7/19/2013 2:30:28 PM	TEXAS INSTRUMENTS	

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